

FR4-TLM140 (mt)

High Thermal resistance Epoxy Laminate and Prepreg

TLM-140(mt) products are manufactured with a unique high performance epoxy resin reinforced with electrical grade (E-glass) glass fabric. TLM-140(mt) offers enhanced thermal resistance due to a high Tg value, Tg 140 °C and achieve flammability class of UL94V-0.

These materials are compatible with the AOI process and exhibit the UV block characteristic.

TLM-140(mt) also exhibit superior chemical resistance, thermal stability and CAF resistance. CCL and PCB can pass through Lead free solder process.

Performance and Processing Advantages

- High performance epoxy blend which yields a higher heat resistance
- Superior dielectric thickness control
- Wide processing window for maximum lamination performance
- Enhanced thermal and chemical resistance
- Compatible with automatic optical inspection process
- UV-block feature
- Lead free solder process compatible
- CAF-Resistance
- Low CTE-Z provide excellent reliability in thermal cycle test
- Meet IPC-4101E /101 specifications

Availability

Thickness: 0.0025" [0.0635 mm] to 0.125" [3.2 mm]

Size: 40"x48", 42"x42", 42"x48", 48"x48", 54"x48"

Option: special size available.

Copper Foil Cladding: Grade 3 (HTE), 0.5 to 3.0 oz.

Option: Low profile & very low profile copper foil.

Prepreg: Available in roll form

Glass Styles: 0106, 1080, 2313, 2116, 1500 and 7628

Industry Approvals

UL-Recognized – FR-4, File Number E174552



TLM-140_(mt) TYPICAL LAMINATE PROPERTIES

Property		UNITS	Specification	Typical Value	CONDITION	Test Method (IPC-TM-650 or As noted)
Glass Transition Temperature (Tg) by DSC, spec minimum		°C	140 +/- 5	142	E-2/105	2.4.25
Decomposition Temperature (Td)		°C	325 min.	340	TGA	ASTM D3850
TD-260		Minutes	30 min.	> 60	TMA	2.4.24.1
TD-288		Minutes	5 min.	> 50	TMA	2.4.24.1
CTE X-Axis	Ambient to Tg	ppm/°C	-	13	TMA	2.4.24
	Y-Axis		-	15		
CTE Z-Axis	Pre-Tg		60 max.	~ 45		
	Post-Tg	ppm/°C	300 max.	~ 200	TMA	2.4.24
	50 - 260 °C		4.0 % max.	150 (3.3 %)		
Thermal Stress	Unetched	Seconds	Pass visual	>200	288°C solder float x 10 sec.	2.4.13.1
	Etched		Pass visual	>200		
Thermal Conductivity		W/mK	-	0.35	-	ASTM D5930
Peel Strength (spec minimum)	1.0 oz. (35 micron)	Lb/inch (N/mm)	6.0 (1.05)	8-10 (1.40-1.80)	After thermal stress	2.4.8
Dielectric Constant (DK)	1 MHz	-	5.4 max.	4.85	C-24/23/50	2.5.5.3
Loss Tangent (Df)	1 MHz	-	0.035 max.	0.020	C-24/23/50	2.5.5.3
Volume Resistivity		Mohm-cm	10 ⁶	3 x 10 ⁹	C-96/35/90	2.5.17.1
Surface Resistivity		Mohm	10 ⁴	1 x 10 ⁸	C-96/35/90	2.5.17.1
Dielectric Breakdown, spec minimum		kV	40 min.	80	D-48/50	2.5.6
Arc resistance		Seconds	60 min.	125	D-48/50	2.5.1
Comparative Tracking Index (CTI)		Volts	-	175-250 (CL=3)	IEC 60112	UL-746A ASTM D3638
Moisture Absorption		%	0.35 max.	0.15	E1/105+ D-24/23	2.6.2.1
Flexural Strength	CW	psi	50,000 min.	65,000	As received	2.4.4
	LW		60,000 min.	75,000		
Flammability		rating	V-0 min.	V-0	C-24/23/50+E-24/125	UL-94
Bow & Twist		%	0.75 max.	0.30	As received/Etched	2.4.22.1

Material Thickness Tested 1.5mm thickness , Cu 1/1 Oz.



TLM-140(mt) PREPREG TYPICAL PROPERTY VALUES

Fabric Style ¹	Resin Content ² (%)	Resin Flow ² (%)	Volatile Content ³ (%)	Gel Time ² (sec)	Scale flow Thickness ²		After Pressed Thickness ²	
					mil	mm	mil	mm
106M	75 ± 3.0	46 ± 6.0	0.50 max	100 ± 20	-	-	2.6 ± 0.4	0.066 ± 0.01
1080LRC	63 ± 3.0	37 ± 6.0			2.5 ± 0.4	0.064 ± 0.01	2.7 ± 0.4	0.069 ± 0.01
1080MRC	66 ± 3.0	41 ± 6.0			2.6 ± 0.4	0.066 ± 0.01	2.9 ± 0.4	0.074 ± 0.01
1080HRC	68 ± 3.0	44 ± 6.0			2.6 ± 0.4	0.066 ± 0.01	3.1 ± 0.4	0.079 ± 0.01
2313MRC	57 ± 3.0	35 ± 6.0			3.4 ± 0.4	0.086 ± 0.01	4.0 ± 0.4	0.102 ± 0.01
2116MRC	55 ± 3.0	33 ± 5.0			4.0 ± 0.4	0.102 ± 0.01	5.0 ± 0.4	0.127 ± 0.01
2116HRC	57 ± 3.0	36 ± 5.0			4.2 ± 0.4	0.107 ± 0.01	5.5 ± 0.4	0.140 ± 0.01
7628LRC	41 ± 3.0	19 ± 5.0			6.65 ± 0.4	0.169 ± 0.01	7.0 ± 0.4	0.178 ± 0.01
7628MRC	43 ± 3.0	21 ± 5.0			6.7 ± 0.4	0.170 ± 0.01	7.3 ± 0.4	0.185 ± 0.01
7628HRC	47 ± 3.0	26 ± 5.0			6.7 ± 0.4	0.170 ± 0.01	7.9 ± 0.4	0.201 ± 0.01
7628VHRC	48 ± 3.0	29 ± 5.0			6.7 ± 0.4	0.170 ± 0.01	8.2 ± 0.4	0.208 ± 0.01
7629URC	53 ± 3.0	34 ± 5.0			7.2 ± 0.4	0.183 ± 0.01	9.2 ± 0.4	0.233 ± 0.01

Note: 1 Other fabric styles are available upon request.

2 Property values are adjustable for special processing needs

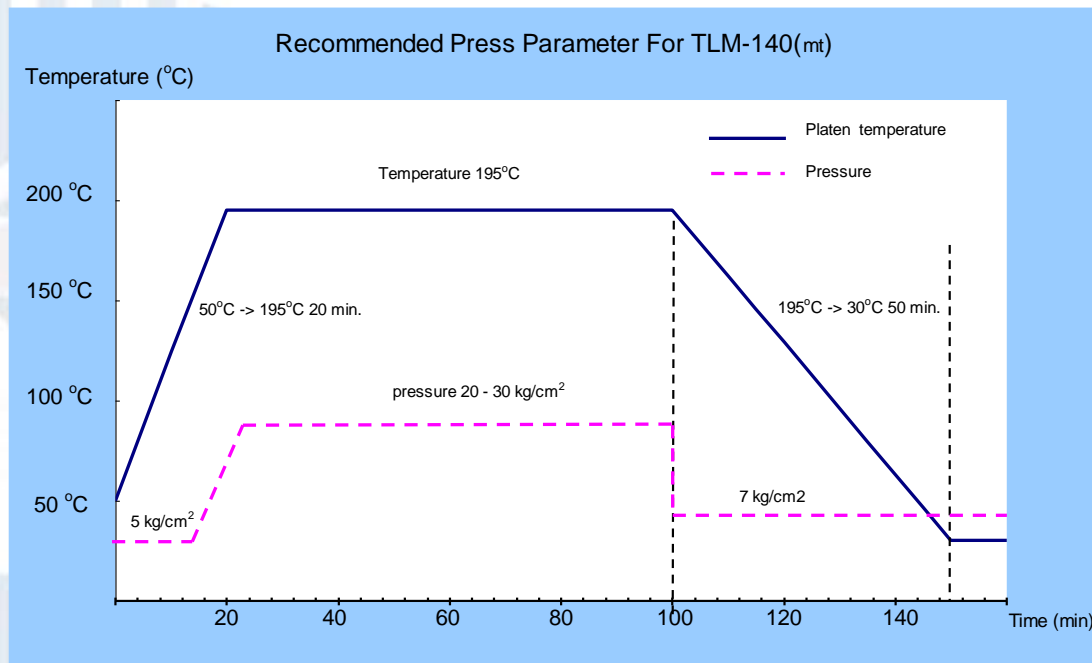
3 Volatile content for all prepregs is less than 0.5%

Storage condition:

- Prepreg properties will maintained for 3 months when keep it under 23°C and under 50%RH
- Beware of moisture, always keep it wrapped in damp proof material.

Recommendation

Press Cycle:



Cushion: Craft paper 162 g/m² top and bottom 9-12 sheets each
 Number of sheets: 6-8 layers

Suggestions:

1. Product heating rate : 1.8~2.3°C/min (80 -> 140°C) is acceptable.
2. Cure time : product temperature over 180°C (cure time) must be hold for at least 60 minutes.
3. Maximum pressure : 20 -30 kg/cm²
 The pressure should be kept below 7 kg/cm² during cooling to ambient temperature.
4. Product cooling rate : kept under 2°C/min

Note : This press cycle is just recommendation only.
 PCB Manufacturer may adjust it based on genuine process .

PCB packaging:

PCB packaging shall be a proper packaging to prevent moisture uptake by PCB with vacuum seal condition include adequate desiccant material to prevent PCB from moisture which diffuse in the packaging material. Using the right packaging materials and maintain in a good condition, PCB's can be stored for up to one year without absorbing excess moisture.